

## C1-007

### Usage: High-temperature processing of electronic components.

- Maximum working temperature of 360°C and 600°C, oxygen concentration below 20ppm.
- Program operation function, with both automatic and manual operation modes.
- Rapid heating and cooling, cooling can through both air cooling and air cooling with water cooling.
- Equipped with automatic door lock, digital pressure gauge, digital flow meter, etc.
- In terms of safety, equipped with automatic overheating prevention, overheating preventer, nitrogen pressure abnormality, nitrogen flow abnormality, over-current and leakage protection circuit breaker, etc.

#### Specifications

Model	Inert Ovens C1-007	
Temp. control range	Room temp. +30 ~ 360°C	Room temp. +50 ~ 600°C
Temp. distribution accuracy	±4.0°C (at 360°C)	±8.0°C (at 600°C)
Temperature rise time	60min (RT ~ 360°C)	90min (RT ~ 600°C)
Temperature fall time	90min (360°C ~ 50°C)	120min (600°C ~ 50°C)
Oxygen concentration	Below 20ppm	
Oxygen concentration fall time	Approx. 45 min	
Operation functions	Fixed temp. operation, program operation	
Accessory	Nitrogen introduction device, water cooling device, differential pressure gauge, etc.	
Internal dimensions	W600×D600×H600mm	
Power supply	3-phase AC380V	



## C1-008

### Usage: Post-photolithography process, photoresist curing.

- Maximum working temperature of 360°C and 600°C, class 100 of cleanliness, oxygen concentration below 20ppm.
- Program operation function, with both automatic and manual operation modes.
- Rapid heating and cooling, cooling can through both air cooling and air cooling with water cooling.
- Equipped with automatic door lock, digital pressure gauge, digital flow meter, etc.
- All stainless steel material.
- In terms of safety, equipped with automatic overheating prevention, overheating preventer, nitrogen pressure abnormality, nitrogen flow abnormality, over-current and leakage protection circuit breaker, etc.

#### Specifications

Model	Clean Inert Ovens C1-008	
Temp. control range	Room temp. +30 ~ 360°C	Room temp. +50 ~ 500°C
Temp. distribution accuracy	±4.0°C (at 360°C)	±8.0°C (at 500°C)
Temperature rise time	60min (RT ~ 360°C)	90min (RT ~ 500°C)
Temperature fall time	90min (360°C ~ 50°C)	120min (500°C ~ 50°C)
Oxygen concentration	Below 20ppm	
Oxygen concentration fall time	Approx. 45 min	
Cleanliness	Class 100	
Accessory	Nitrogen introduction device, water cooling device, differential pressure gauge, etc.	
Internal dimensions	W600×D600×H600mm	
Power supply	3-phase AC380V	



Forced convection

Natural convection

Fine

Options

For labware

Explosion-proof

Far infrared heating

Anaerobic

Clean

Vacuum

Semiconductor & electronics

Battery

Flat panel display

Others